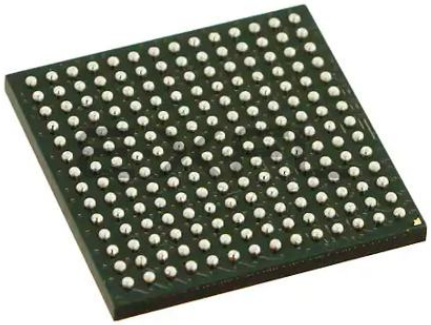

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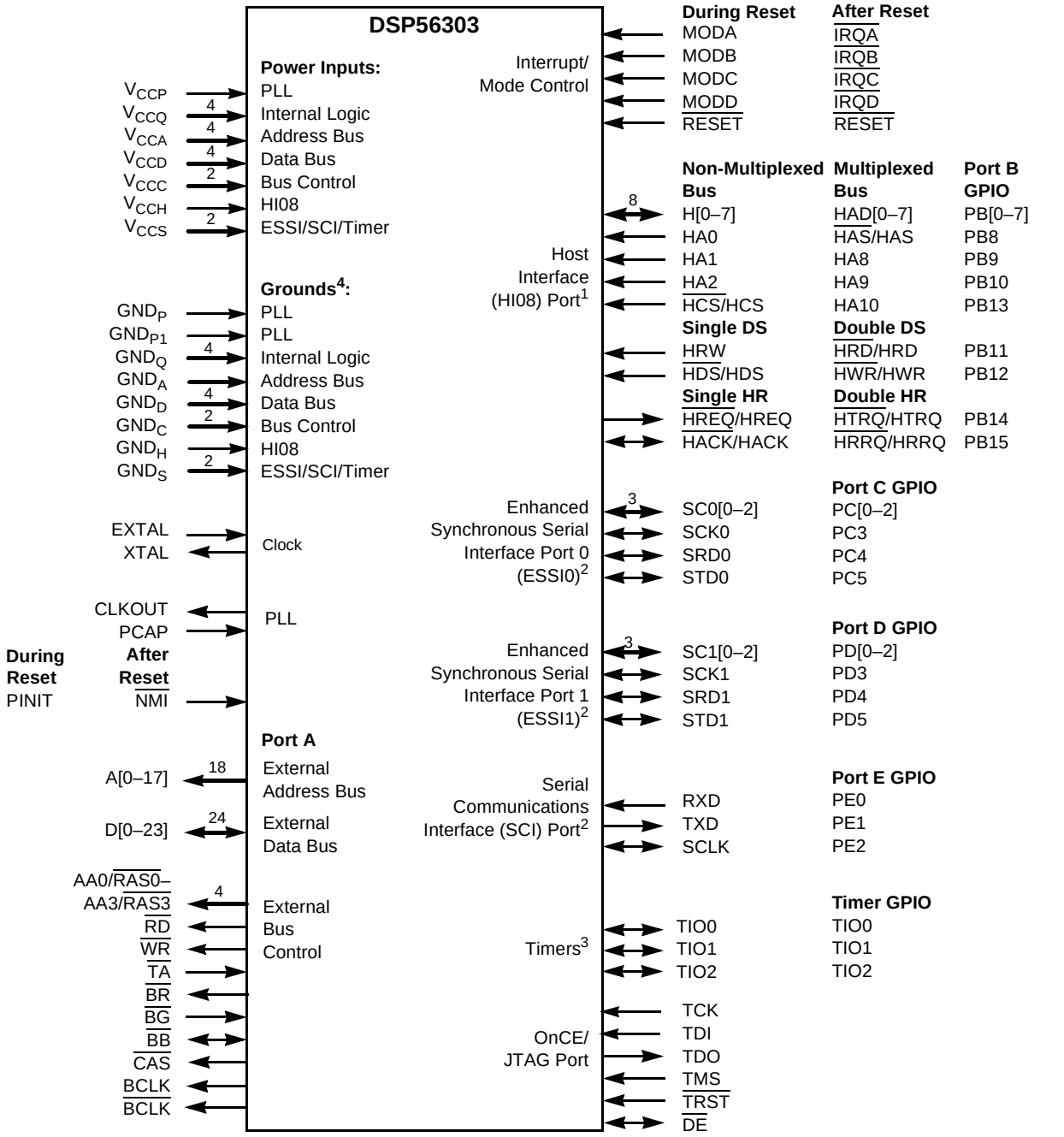
Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Obsolete
Type	Fixed Point
Interface	Host Interface, SSI, SCI
Clock Rate	160MHz
Non-Volatile Memory	ROM (576B)
On-Chip RAM	576kB
Voltage - I/O	3.30V
Voltage - Core	1.80V
Operating Temperature	-40°C ~ 100°C
Mounting Type	Surface Mount
Package / Case	196-LBGA
Supplier Device Package	196-LBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/spakxcl307vl160

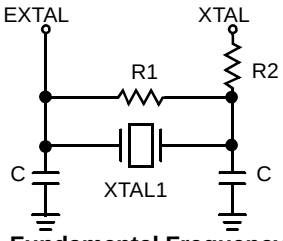


Notes:
1. The HI08 port supports a non-multiplexed or a multiplexed bus, single or double Data Strobe (DS), and single or double Host Request (HR) configurations. Since each of these modes is configured independently, any combination of these modes is possible. These HI08 signals can also be configured alternatively as GPIO signals (PB[0–15]). Signals with dual designations (for example, HAS/HAS) have configurable polarity.
2. The ESSI0, ESSI1, and SCI signals are multiplexed with the Port C GPIO signals (PC[0–5]), Port D GPIO signals (PD[0–5]), and Port E GPIO signals (PE[0–2]), respectively.
3. TIO[0–2] can be configured as GPIO signals.
4. Ground connections shown in this figure are for the TQFP package. In the MAP-BGA package, in addition to the GND_P and GND_{P1} connections, there are 64 GND connections to a common internal package ground plane.

Figure 1-1. Signals Identified by Functional Group

2.6.2 External Clock Operation

The DSP56303 system clock is derived from the on-chip oscillator or is externally supplied. To use the on-chip oscillator, connect a crystal and associated resistor/capacitor components to EXTAL and XTAL; examples are shown in **Figure 2-1**.



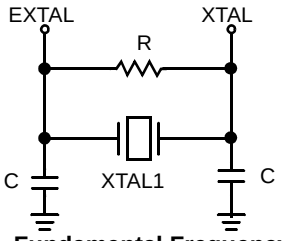
Fundamental Frequency Fork Crystal Oscillator

Note: Ensure that in the PCTL Register:
- XTLD (bit 16) = 0
- If $f_{OSC} \leq 200$ kHz, XTLR (bit 15) = 1

Suggested Component Values:

f_{OSC} = 32.768 kHz
R1 = 3.9 MΩ ± 10%
C = 22 pF ± 20%
R2 = 200 kΩ ± 10%

Calculations are for a 32.768 kHz crystal with the following parameters:
- load capacitance (C_L) of 12.5 pF,
- shunt capacitance (C_0) of 1.8 pF,
- series resistance of 40 kΩ, and
- drive level of 1 µW.



Fundamental Frequency Crystal Oscillator

Note: Ensure that in the PCTL Register:
- XTLD (bit 16) = 0
- If $f_{OSC} > 200$ kHz, XTLR (bit 15) = 0

Suggested Component Values:

f_{OSC} = 4 MHz	f_{OSC} = 20 MHz
R = 680 kΩ ± 10%	R = 680 kΩ ± 10%
C = 56 pF ± 20%	C = 22 pF ± 20%

Calculations are for a 4/20 MHz crystal with the following parameters:
- C_L of 30/20 pF,
- C_0 of 7/6 pF,
- series resistance of 100/20 Ω, and
- drive level of 2 mW.

Figure 2-1. Crystal Oscillator Circuits

If an externally-supplied square wave voltage source is used, disable the internal oscillator circuit during bootup by setting XTLD (PCTL Register bit 16 = 1—see the *DSP56303 User's Manual*). The external square wave source connects to EXTAL; XTAL is not physically connected to the board or socket. **Figure 2-2** shows the relationship between the EXTAL input and the internal clock and CLKOUT.

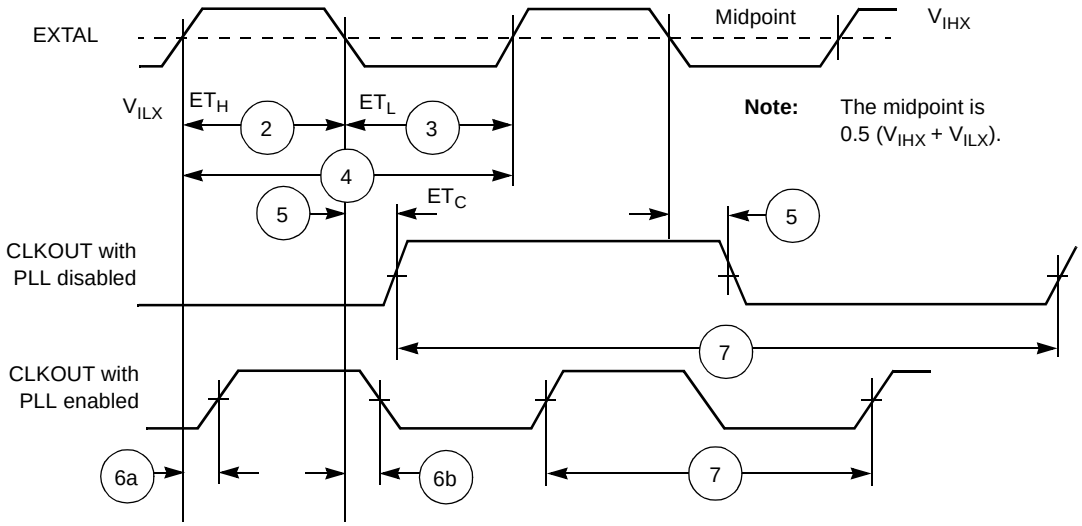


Figure 2-2. External Clock Timing

Table 2-8. SRAM Read and Write Accesses (Continued)

No.	Characteristics	Symbol	Expression[1]	100 MHz		Unit
				Min	Max	
111	$\overline{WR}$ deassertion to data high impedance	—	$0.25 \times T_C + 0.2$ [1 ≤ WS ≤ 3]	—	2.7	ns
			$1.25 \times TC + 0.2$ [4 ≤ WS ≤ 7]	—	12.7	ns
			$2.25 \times T_C + 0.2$ [WS > 8]	—	22.7	ns
112	Previous $\overline{RD}$ deassertion to data active (write)	—	$1.25 \times T_C - 4.0$ [1 ≤ WS ≤ 3]	8.5	—	ns
			$2.25 \times T_C - 4.0$ [4 ≤ WS ≤ 7]	18.5	—	ns
			$3.25 \times T_C - 4.0$ [WS > 8]	28.5	—	ns
113	$\overline{RD}$ deassertion time	—	$0.75 \times T_C - 4.0$ [1 ≤ WS ≤ 3]	3.5	—	ns
			$1.75 \times T_C - 4.0$ [4 ≤ WS ≤ 7]	13.5	—	ns
			$2.75 \times T_C - 4.0$ [WS ≥ 8]	23.5	—	ns
114	$\overline{WR}$ deassertion time	—	$0.5 \times T_C - 4.0$ [WS = 1]	1.0	—	ns
			$T_C - 4.0$ [2 ≤ WS ≤ 3]	6.0	—	ns
			$2.5 \times T_C - 4.0$ [4 ≤ WS ≤ 7]	21.0	—	ns
			$3.5 \times T_C - 4.0$ [WS ≥ 8]	31.0	—	ns
115	Address valid to $\overline{RD}$ assertion	—	$0.5 \times T_C - 4.0$	1.0	—	ns
116	$\overline{RD}$ assertion pulse width	—	$(WS + 0.25) \times T_C - 4.0$	8.5	—	ns
117	$\overline{RD}$ deassertion to address not valid	—	$0.25 \times T_C - 2.0$ [1 ≤ WS ≤ 3]	0.5	—	ns
			$1.25 \times T_C - 2.0$ [4 ≤ WS ≤ 7]	10.5	—	ns
			$2.25 \times T_C - 2.0$ [WS ≥ 8]	20.5	—	ns
118	$\overline{TA}$ setup before $\overline{RD}$ or $\overline{WR}$ deassertion[4]	—	$0.25 \times T_C + 2.0$	4.5	—	ns
119	$\overline{TA}$ hold after $\overline{RD}$ or $\overline{WR}$ deassertion	—	—	0	—	ns

Notes:
1. WS is the number of wait states specified in the BCR. An expression is used to compute the number listed as the minimum or maximum value, as appropriate.
2. Timings 100, 107 are guaranteed by design, not tested.
3. All timings for 100 MHz are measured from $0.5 \times Vcc$ to $0.5 \times Vcc$.
4. Timing 118 is relative to the deassertion edge of $\overline{RD}$ or $\overline{WR}$ even if $\overline{TA}$ remains asserted.
5. V_{CC} = 3.3 V ± 0.3 V; T_J = –40°C to +100°C, C_L = 50 pF

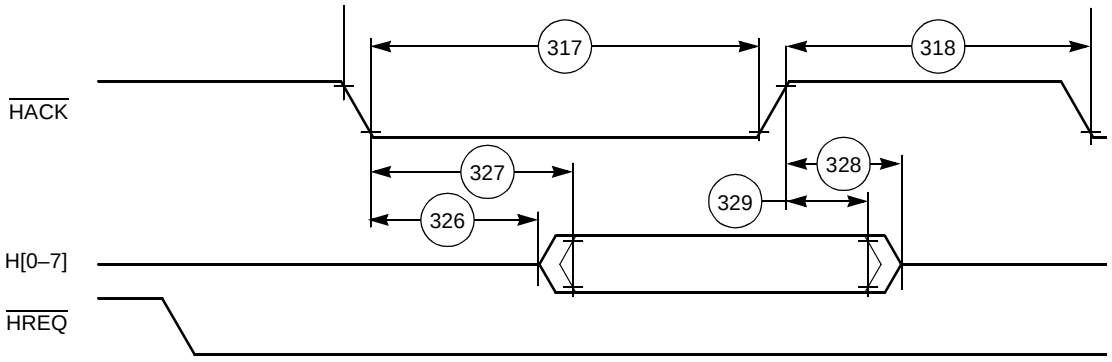
Table 2-12. DRAM Out-of-Page and Refresh Timings, Fifteen Wait States[1,2]

No.	Characteristics	Symbol	Expression[3]	100 MHz		Unit
				Min	Max	
157	Random read or write cycle time	t_{RC}	$16 \times T_C$	160.0	—	ns
158	$\overline{RAS}$ assertion to data valid (read)	t_{RAC}	$8.25 \times T_C - 5.7$	—	76.8	ns
159	$\overline{CAS}$ assertion to data valid (read)	t_{CAC}	$4.75 \times T_C - 5.7$	—	41.8	ns
160	Column address valid to data valid (read)	t_{AA}	$5.5 \times T_C - 5.7$	—	49.3	ns
161	$\overline{CAS}$ deassertion to data not valid (read hold time)	t_{OFF}	0.0	0.0	—	ns
162	$\overline{RAS}$ deassertion to $\overline{RAS}$ assertion	t_{RP}	$6.25 \times T_C - 4.0$	58.5	—	ns
163	$\overline{RAS}$ assertion pulse width	t_{RAS}	$9.75 \times T_C - 4.0$	93.5	—	ns
164	$\overline{CAS}$ assertion to $\overline{RAS}$ deassertion	t_{RSH}	$6.25 \times T_C - 4.0$	58.5	—	ns
165	$\overline{RAS}$ assertion to $\overline{CAS}$ deassertion	t_{CSH}	$8.25 \times T_C - 4.0$	78.5	—	ns
166	$\overline{CAS}$ assertion pulse width	t_{CAS}	$4.75 \times T_C - 4.0$	43.5	—	ns
167	$\overline{RAS}$ assertion to $\overline{CAS}$ assertion	t_{RCD}	$3.5 \times T_C \pm 2$	33.0	37.0	ns
168	$\overline{RAS}$ assertion to column address valid	t_{RAD}	$2.75 \times T_C \pm 2$	25.5	29.5	ns
169	$\overline{CAS}$ deassertion to $\overline{RAS}$ assertion	t_{CRP}	$7.75 \times T_C - 4.0$	73.5	—	ns
170	$\overline{CAS}$ deassertion pulse width	t_{CP}	$6.25 \times T_C - 6.0$	56.5	—	ns
171	Row address valid to $\overline{RAS}$ assertion	t_{ASR}	$6.25 \times T_C - 4.0$	58.5	—	ns
172	$\overline{RAS}$ assertion to row address not valid	t_{RAH}	$2.75 \times T_C - 4.0$	23.5	—	ns
173	Column address valid to $\overline{CAS}$ assertion	t_{ASC}	$0.75 \times T_C - 4.0$	3.5	—	ns
174	$\overline{CAS}$ assertion to column address not valid	t_{CAH}	$6.25 \times T_C - 4.0$	58.5	—	ns
175	$\overline{RAS}$ assertion to column address not valid	t_{AR}	$9.75 \times T_C - 4.0$	93.5	—	ns
176	Column address valid to $\overline{RAS}$ deassertion	t_{RAL}	$7 \times T_C - 4.0$	66.0	—	ns
177	$\overline{WR}$ deassertion to $\overline{CAS}$ assertion	t_{RCS}	$5 \times T_C - 3.8$	46.2	—	ns
178	$\overline{CAS}$ deassertion to $\overline{WR}$[4] assertion	t_{RCH}	$1.75 \times T_C - 3.7$	13.8	—	ns
179	$\overline{RAS}$ deassertion to $\overline{WR}$[4] assertion	t_{RRH}	$0.25 \times T_C - 2.0$	0.5	—	ns
180	$\overline{CAS}$ assertion to $\overline{WR}$ deassertion	t_{WCH}	$6 \times T_C - 4.2$	55.8	—	ns
181	$\overline{RAS}$ assertion to $\overline{WR}$ deassertion	t_{WCR}	$9.5 \times T_C - 4.2$	90.8	—	ns
182	$\overline{WR}$ assertion pulse width	t_{WP}	$15.5 \times T_C - 4.5$	150.5	—	ns
183	$\overline{WR}$ assertion to $\overline{RAS}$ deassertion	t_{RWL}	$15.75 \times T_C - 4.3$	153.2	—	ns
184	$\overline{WR}$ assertion to $\overline{CAS}$ deassertion	t_{CWL}	$14.25 \times T_C - 4.3$	138.2	—	ns
185	Data valid to $\overline{CAS}$ assertion (write)	t_{DS}	$8.75 \times T_C - 4.0$	83.5	—	ns
186	$\overline{CAS}$ assertion to data not valid (write)	t_{DH}	$6.25 \times T_C - 4.0$	58.5	—	ns
187	$\overline{RAS}$ assertion to data not valid (write)	t_{DHR}	$9.75 \times T_C - 4.0$	93.5	—	ns
188	$\overline{WR}$ assertion to $\overline{CAS}$ assertion	t_{WCS}	$9.5 \times T_C - 4.3$	90.7	—	ns
189	$\overline{CAS}$ assertion to $\overline{RAS}$ assertion (refresh)	t_{CSR}	$1.5 \times T_C - 4.0$	11.0	—	ns
190	$\overline{RAS}$ deassertion to $\overline{CAS}$ assertion (refresh)	t_{RPC}	$4.75 \times T_C - 4.0$	43.5	—	ns
191	$\overline{RD}$ assertion to $\overline{RAS}$ deassertion	t_{ROH}	$15.5 \times T_C - 4.0$	151.0	—	ns
192	$\overline{RD}$ assertion to data valid	t_{GA}	$14 \times T_C - 5.7$	—	134.3	ns
193	$\overline{RD}$ deassertion to data not valid[5]	t_{GZ}		0.0	—	ns
194	$\overline{WR}$ assertion to data active		$0.75 \times T_C - 1.5$	6.0	—	ns
195	$\overline{WR}$ deassertion to data high impedance		$0.25 \times T_C$	—	2.5	ns

Table 2-16. Host Interface Timings[1,2,12] (Continued)

No.	Characteristic[10]	Expression	100 MHz		Unit
			Min	Max	
338	Delay from read data strobe deassertion to host request assertion for “Last Data Register” read[5, 7, 8]	$T_C + 5.3$	15.3	—	ns
339	Delay from write data strobe deassertion to host request assertion for “Last Data Register” write[6, 7, 8]	$1.5 \times T_C + 5.3$	20.3	—	ns
340	Delay from data strobe assertion to host request deassertion for “Last Data Register” read or write (HROD=0)[4, 7, 8]		—	19.3	ns
341	Delay from data strobe assertion to host request deassertion for “Last Data Register” read or write (HROD=1, open drain host request)[4, 7, 8, 9]		—	300.0	ns

Notes:
1. See the Programmer’s Model section in the chapter on the HI08 in the *DSP56303User’s Manual*.
2. In the timing diagrams below, the controls pins are drawn as active low. The pin polarity is programmable.
3. This timing is applicable only if two consecutive reads from one of these registers are executed.
4. The data strobe is Host Read (HRD) or Host Write (HWR) in the Dual Data Strobe mode and Host Data Strobe (HDS) in the Single Data Strobe mode.
5. The read data strobe is HRD in the Dual Data Strobe mode and HDS in the Single Data Strobe mode.
6. The write data strobe is HWR in the Dual Data Strobe mode and HDS in the Single Data Strobe mode.
7. The host request is HREQ in the Single Host Request mode and HRRQ and HTRQ in the Double Host Request mode.
8. The “Last Data Register” is the register at address $7, which is the last location to be read or written in data transfers. This is RXL/TXL in the Big Endian mode (HLEND = 0; HLEND is the Interface Control Register bit 7—ICR[7]), or RXH/TXH in the Little Endian mode (HLEND = 1).
9. In this calculation, the host request signal is pulled up by a 4.7 kΩ resistor in the Open-drain mode.
10. $V_{CC} = 3.3\ V \pm 0.3\ V$; $T_J = -40°C$ to $+100\ °C$, $C_L = 50\ pF$
11. This timing is applicable only if a read from the “Last Data Register” is followed by a read from the RXL, RXM, or RXH registers without first polling RXDF or HREQ bits, or waiting for the assertion of the HREQ signal.
12. After the external host writes a new value to the ICR, the HI08 is ready for operation after three DSP clock cycles ($3 \times Tc$).



Note: The IVR is only read by an MC680xx host processor using non-multiplexed mode.

Figure 2-27. Host Interrupt Vector Register (IVR) Read Timing Diagram

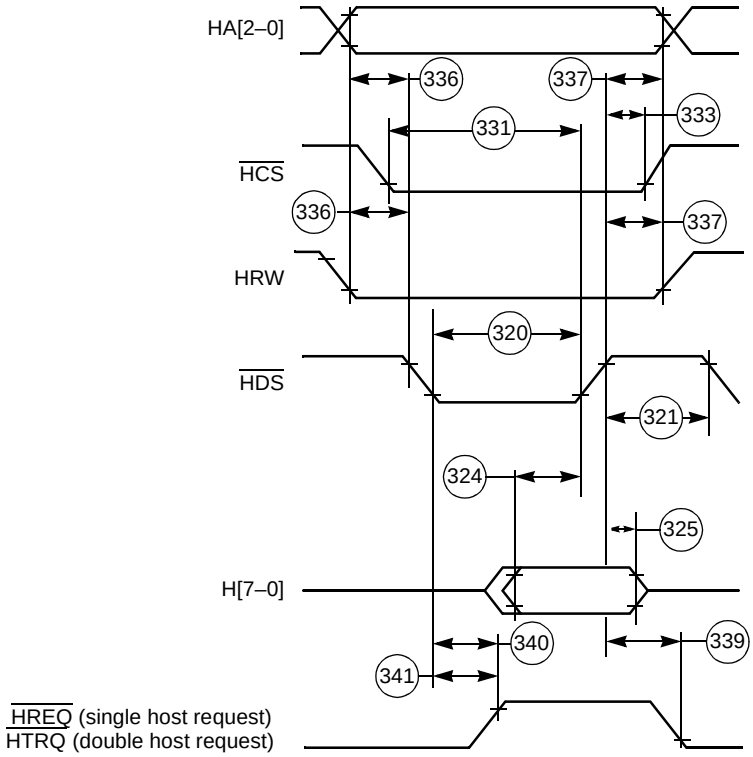


Figure 2-30. Write Timing Diagram, Non-Multiplexed Bus, Single Data Strobe

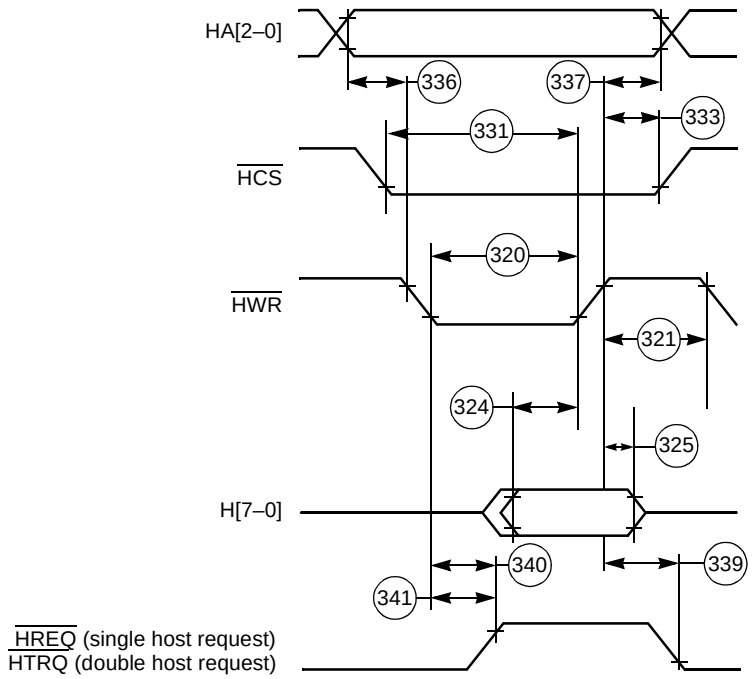


Figure 2-31. Write Timing Diagram, Non-Multiplexed Bus, Double Data Strobe

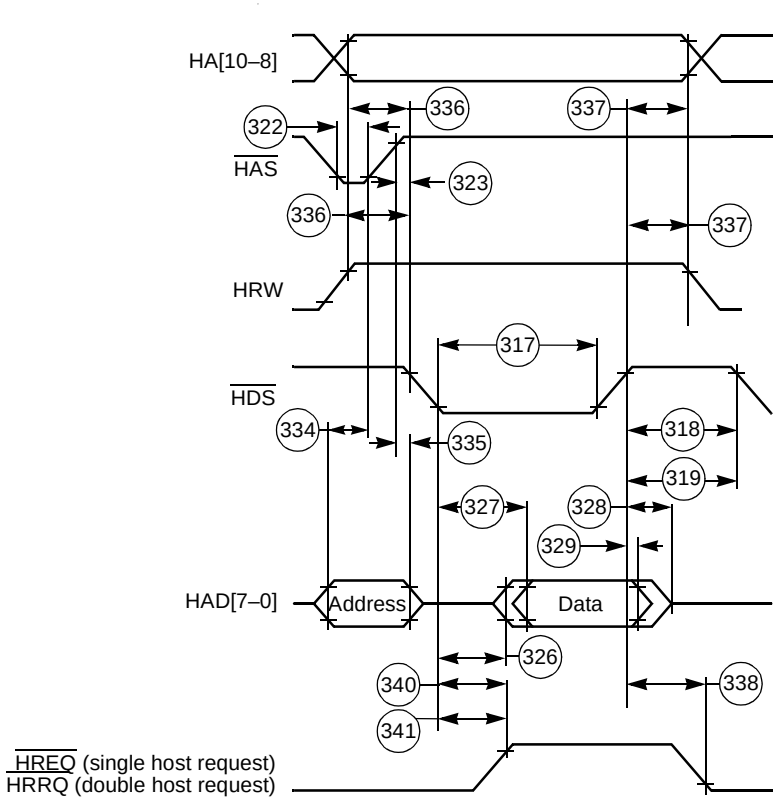


Figure 2-32. Read Timing Diagram, Multiplexed Bus, Single Data Strobe

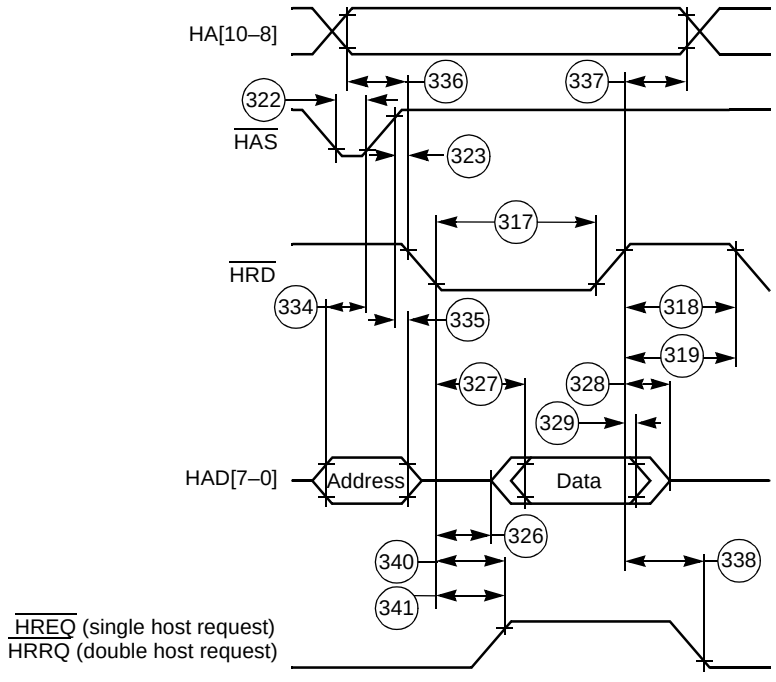


Figure 2-33. Read Timing Diagram, Multiplexed Bus, Double Data Strobe

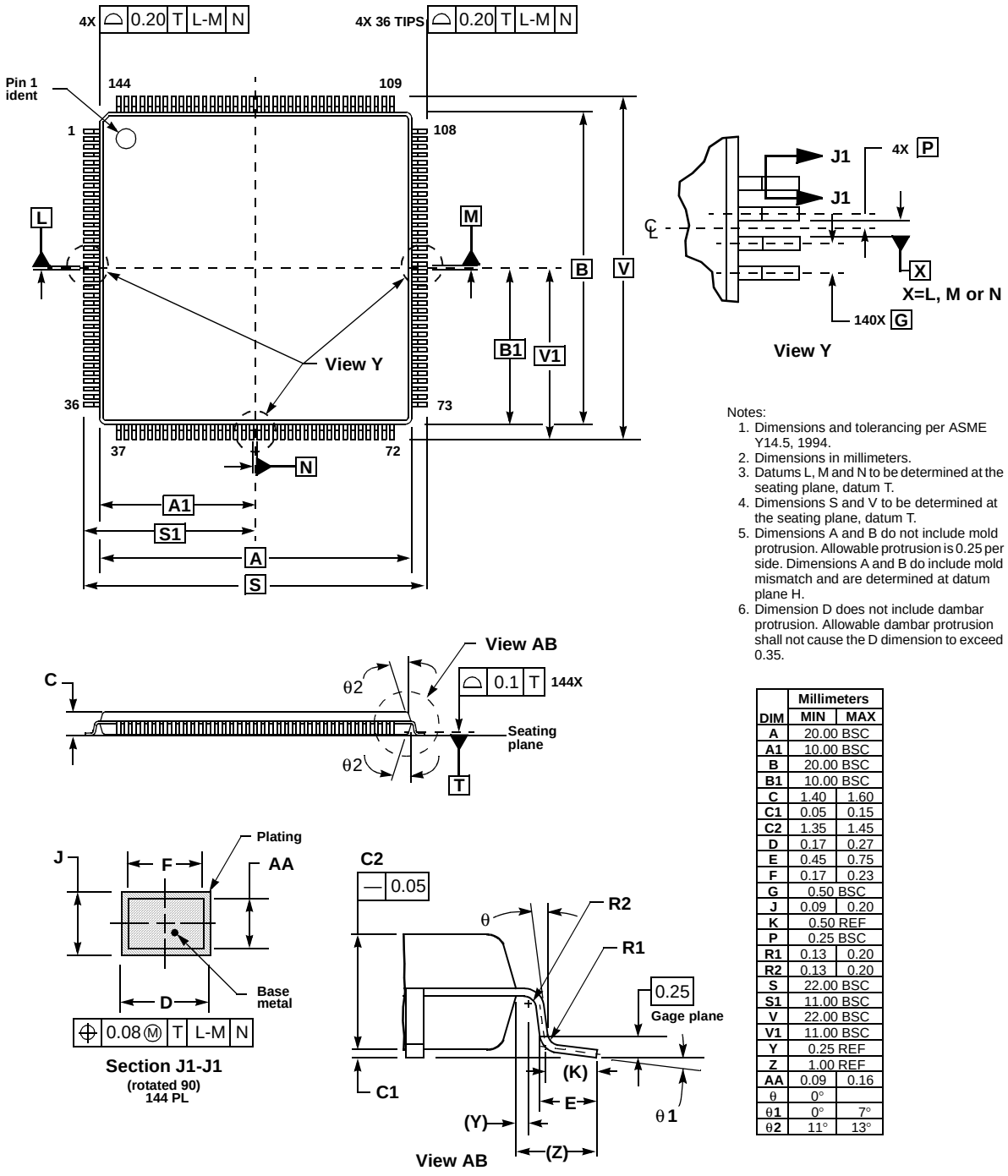
Table 3-1. DSP56303 TQFP Signal Identification by Pin Number

Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name
1	SRD1 or PD4	26	GND_S	51	AA2/$\overline{RAS2}$
2	STD1 or PD5	27	TIO2	52	$\overline{CAS}$
3	SC02 or PC2	28	TIO1	53	XTAL
4	SC01 or PC1	29	TIO0	54	GND_Q
5	$\overline{DE}$	30	$\overline{HCS}$/HCS, HA10, or PB13	55	EXTAL
6	PINIT/$\overline{NMI}$	31	HA2, HA9, or PB10	56	V_{CCQ}
7	SRD0 or PC4	32	HA1, HA8, or PB9	57	V_{CCC}
8	V_{CCS}	33	HA0, $\overline{HAS}$/HAS, or PB8	58	GND_C
9	GND_S	34	H7, HAD7, or PB7	59	CLKOUT
10	STD0 or PC5	35	H6, HAD6, or PB6	60	BCLK
11	SC10 or PD0	36	H5, HAD5, or PB5	61	$\overline{BCLK}$
12	SC00 or PC0	37	H4, HAD4, or PB4	62	$\overline{TA}$
13	RXD or PE0	38	V_{CCH}	63	$\overline{BR}$
14	TXD or PE1	39	GND_H	64	$\overline{BB}$
15	SCLK or PE2	40	H3, HAD3, or PB3	65	V_{CCC}
16	SCK1 or PD3	41	H2, HAD2, or PB2	66	GND_C
17	SCK0 or PC3	42	H1, HAD1, or PB1	67	$\overline{WR}$
18	V_{CCQ}	43	H0, HAD0, or PB0	68	$\overline{RD}$
19	GND_Q	44	$\overline{RESET}$	69	AA1/$\overline{RAS1}$
20	Not Connected (NC), reserved	45	V_{CCP}	70	AA0/$\overline{RAS0}$
21	$\overline{HDS}$/HDS, $\overline{HWR}$/HWR, or PB12	46	PCAP	71	$\overline{BG}$
22	HRW, $\overline{HRD}$/HRD, or PB11	47	GND_P	72	A0
23	$\overline{HACK}$/HACK, $\overline{HRRQ}$/HRRQ, or PB15	48	GND_{P1}	73	A1
24	$\overline{HREQ}$/HREQ, $\overline{HTRQ}$/HTRQ, or PB14	49	Not Connected (NC), reserved	74	V_{CCA}
25	V_{CCS}	50	AA3/$\overline{RAS3}$	75	GND_A

Table 3-2. DSP56303 TQFP Signal Identification by Name (Continued)

Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.
H1	42	$\overline{\text{HRD}}$/HRD	22	PB2	41
H2	41	$\overline{\text{HREQ}}$/HREQ	24	PB3	40
H3	40	$\overline{\text{HRRQ}}$/HRRQ	23	PB4	37
H4	37	HRW	22	PB5	36
H5	36	$\overline{\text{HTRQ}}$/HTRQ	24	PB6	35
H6	35	$\overline{\text{HWR}}$/HWR	21	PB7	34
H7	34	$\overline{\text{IRQA}}$	137	PB8	33
HA0	33	$\overline{\text{IRQB}}$	136	PB9	32
HA1	32	$\overline{\text{IRQC}}$	135	PC0	12
HA10	30	$\overline{\text{IRQD}}$	134	PC1	4
HA2	31	MODA	137	PC2	3
HA8	32	MODB	136	PC3	17
HA9	31	MODC	135	PC4	7
$\overline{\text{HACK}}$/HACK	23	MODD	134	PC5	10
HAD0	43	NC	20	PCAP	46
HAD1	42	NMI	6	PD0	11
HAD2	41	NC	49	PD1	144
HAD3	40	PB0	43	PD2	143
HAD4	37	PB1	42	PD3	16
HAD5	36	PB10	31	PD4	1
HAD6	35	PB11	22	PD5	2
HAD7	34	PB12	21	PE0	13
$\overline{\text{HAS}}$/HAS	33	PB13	30	PE1	14
$\overline{\text{HCS}}$/HCS	30	PB14	24	PE2	15
$\overline{\text{HDS}}$/HDS	21	PB15	23	PINIT	6

3.3 TQFP Package Mechanical Drawing



Notes:
1. Dimensions and tolerancing per ASME Y14.5, 1994.
2. Dimensions in millimeters.
3. Datums L, M and N to be determined at the seating plane, datum T.
4. Dimensions S and V to be determined at the seating plane, datum T.
5. Dimensions A and B do not include mold protrusion. Allowable protrusion is 0.25 per side. Dimensions A and B do include mold mismatch and are determined at datum plane H.
6. Dimension D does not include dambar protrusion. Allowable dambar protrusion shall not cause the D dimension to exceed 0.35.

	Millimeters	
DIM	MIN	MAX
A	20.00 BSC	
A1	10.00 BSC	
B	20.00 BSC	
B1	10.00 BSC	
C	1.40	1.60
C1	0.05	0.15
C2	1.35	1.45
D	0.17	0.27
E	0.45	0.75
F	0.17	0.23
G	0.50 BSC	
J	0.09	0.20
K	0.50 REF	
P	0.25 BSC	
R1	0.13	0.20
R2	0.13	0.20
S	22.00 BSC	
S1	11.00 BSC	
V	22.00 BSC	
V1	11.00 BSC	
Y	0.25 REF	
Z	1.00 REF	
AA	0.09	0.16
θ	0°	
θ1	0°	7°
θ2	11°	13°

CASE 918-03
ISSUE C

Figure 3-3. DSP56303 Mechanical Information, 144-pin TQFP Package

3.4 MAP-BGA Package Description

Top and bottom views of the MAP-BGA package are shown in **Figure 3-4** and **Figure 3-5** with their pin-outs.

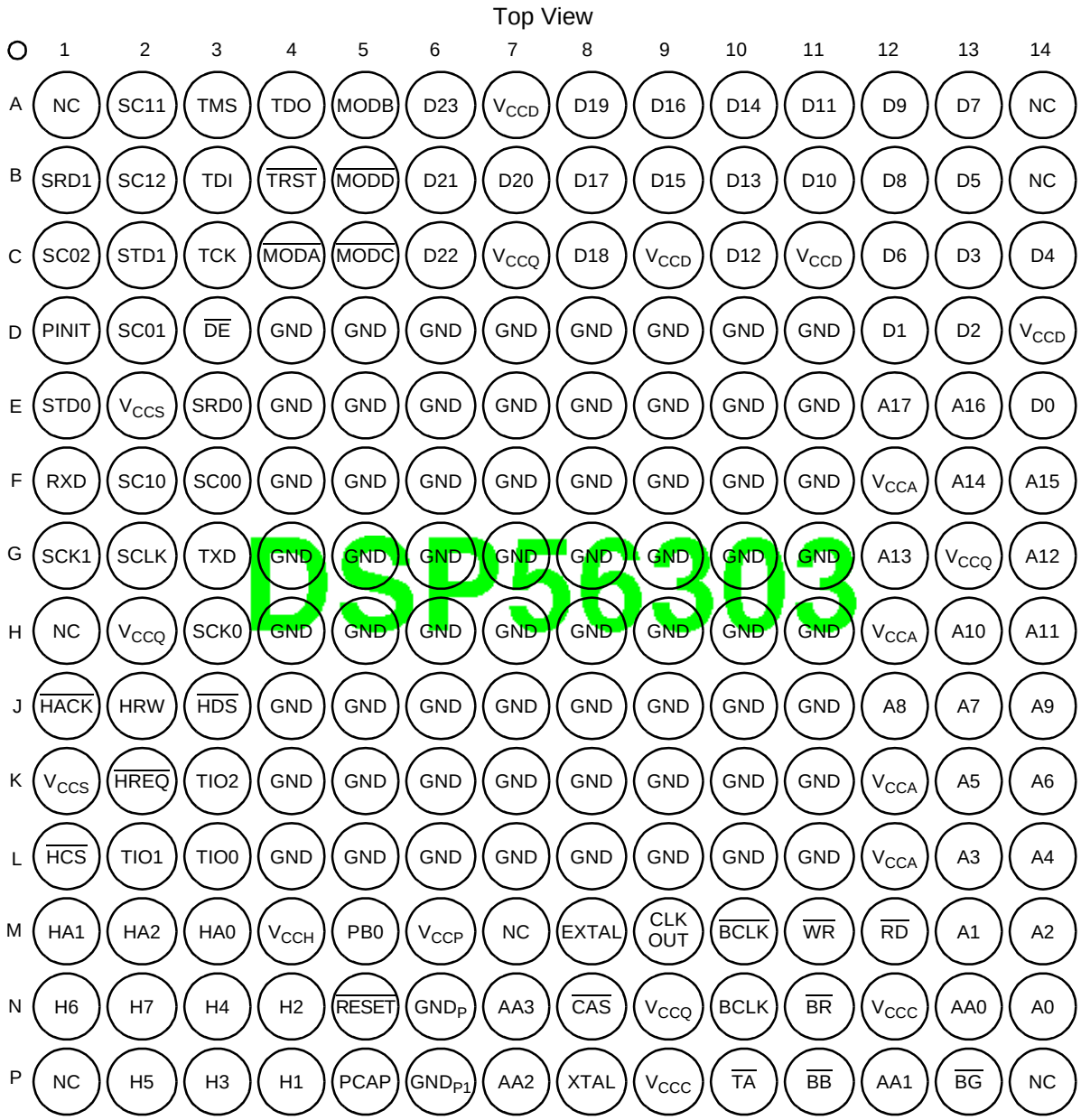


Figure 3-4. DSP56303 Molded Array Process-Ball Grid Array (MAP-BGA), Top View

Table 3-4. DSP56303 MAP-BGA Signal Identification by Name

Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.
A0	N14	$\overline{BG}$	P13	D7	A13
A1	M13	$\overline{BR}$	N11	D8	B12
A10	H13	$\overline{CAS}$	N8	D9	A12
A11	H14	CLKOUT	M9	$\overline{DE}$	D3
A12	G14	D0	E14	EXTAL	M8
A13	G12	D1	D12	GND	D4
A14	F13	D10	B11	GND	D5
A15	F14	D11	A11	GND	D6
A16	E13	D12	C10	GND	D7
A17	E12	D13	B10	GND	D8
A2	M14	D14	A10	GND	D9
A3	L13	D15	B9	GND	D10
A4	L14	D16	A9	GND	D11
A5	K13	D17	B8	GND	E4
A6	K14	D18	C8	GND	E5
A7	J13	D19	A8	GND	E6
A8	J12	D2	D13	GND	E7
A9	J14	D20	B7	GND	E8
AA0	N13	D21	B6	GND	E9
AA1	P12	D22	C6	GND	E10
AA2	P7	D23	A6	GND	E11
AA3	N7	D3	C13	GND	F4
$\overline{BB}$	P11	D4	C14	GND	F5
$\overline{BCLK}$	M10	D5	B13	GND	F6
BCLK	N10	D6	C12	GND	F7

Table 3-4. DSP56303 MAP-BGA Signal Identification by Name (Continued)

Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.
HRW	J2	PB14	K2	PE2	G2
$\overline{\text{HTRQ}}$/HTRQ	K2	PB15	J1	PINIT	D1
$\overline{\text{HWR}}$/HWR	J3	PB2	N4	$\overline{\text{RAS0}}$	N13
$\overline{\text{IRQA}}$	C4	PB3	P3	$\overline{\text{RAS1}}$	P12
$\overline{\text{IRQB}}$	A5	PB4	N3	$\overline{\text{RAS2}}$	P7
$\overline{\text{IRQC}}$	C5	PB5	P2	$\overline{\text{RAS3}}$	N7
$\overline{\text{IRQD}}$	B5	PB6	N1	$\overline{\text{RD}}$	M12
MODA	C4	PB7	N2	$\overline{\text{RESET}}$	N5
MODB	A5	PB8	M3	RXD	F1
MODC	C5	PB9	M1	SC00	F3
MODD	B5	PC0	F3	SC01	D2
NC	A1	PC1	D2	SC02	C1
NC	A14	PC2	C1	SC10	F2
NC	B14	PC3	H3	SC11	A2
NC	H1	PC4	E3	SC12	B2
NC	M7	PC5	E1	SCK0	H3
NC	P1	PCAP	P5	SCK1	G1
NC	P14	PD0	F2	SCLK	G2
NMI	D1	PD1	A2	SRD0	E3
PB0	M5	PD2	B2	SRD1	B1
PB1	P4	PD3	G1	STD0	E1
PB10	M2	PD4	B1	STD1	C2
PB11	J2	PD5	C2	$\overline{\text{TA}}$	P10
PB12	J3	PE0	F1	TCK	C3
PB13	L1	PE1	G3	TDI	B3

A complicating factor is the existence of three common ways to determine the junction-to-case thermal resistance in plastic packages.

- To minimize temperature variation across the surface, the thermal resistance is measured from the junction to the outside surface of the package (case) closest to the chip mounting area when that surface has a proper heat sink.
- To define a value approximately equal to a junction-to-board thermal resistance, the thermal resistance is measured from the junction to the point at which the leads attach to the case.
- If the temperature of the package case (T_T) is determined by a thermocouple, thermal resistance is computed from the value obtained by the equation $(T_J - T_T)/P_D$.

As noted earlier, the junction-to-case thermal resistances quoted in this data sheet are determined using the first definition. From a practical standpoint, that value is also suitable to determine the junction temperature from a case thermocouple reading in forced convection environments. In natural convection, the use of the junction-to-case thermal resistance to estimate junction temperature from a thermocouple reading on the case of the package will yield an estimate of a junction temperature slightly higher than actual temperature. Hence, the new thermal metric, thermal characterization parameter or Ψ_{JT}, has been defined to be $(T_J - T_T)/P_D$. This value gives a better estimate of the junction temperature in natural convection when the surface temperature of the package is used. Remember that surface temperature readings of packages are subject to significant errors caused by inadequate attachment of the sensor to the surface and to errors caused by heat loss to the sensor. The recommended technique is to attach a 40-gauge thermocouple wire and bead to the top center of the package with thermally conductive epoxy.

4.2 Electrical Design Considerations

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for example, either GND or V_{CC}).

Use the following list of recommendations to ensure correct DSP operation.

- Provide a low-impedance path from the board power supply to each V_{CC} pin on the DSP and from the board ground to each GND pin.
- Use at least six 0.01–0.1 µF bypass capacitors positioned as close as possible to the four sides of the package to connect the V_{CC} power source to GND.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{CC} and GND pins are less than 0.5 inch per capacitor lead.
- Use at least a four-layer PCB with two inner layers for V_{CC} and GND.
- Because the DSP output signals have fast rise and fall times, PCB trace lengths should be minimal. This recommendation particularly applies to the address and data buses as well as the $\overline{\text{IRQA}}$, $\overline{\text{IRQB}}$, $\overline{\text{IRQC}}$, $\overline{\text{IRQD}}$, $\overline{\text{TA}}$, and $\overline{\text{BG}}$ pins. Maximum PCB trace lengths on the order of 6 inches are recommended.
- Consider all device loads as well as parasitic capacitance due to PCB traces when you calculate capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{CC} and GND circuits.
- All inputs must be terminated (that is, not allowed to float) by CMOS levels except for the three pins with internal pull-up resistors ($\overline{\text{TRST}}$, TMS, $\overline{\text{DE}}$).
- Take special care to minimize noise levels on the V_{CCP}, GND_P, and GND_{P1} pins.
- The following pins must be asserted after power-up: $\overline{\text{RESET}}$ and $\overline{\text{TRST}}$.
- If multiple DSP devices are on the same board, check for cross-talk or excessive spikes on the supplies due to synchronous operation of the devices.
- $\overline{\text{RESET}}$ must be asserted when the chip is powered up. A stable EXTAL signal should be supplied before deassertion of $\overline{\text{RESET}}$.
- At power-up, ensure that the voltage difference between the 5 V tolerant pins and the chip V_{CC} never exceeds 3.5 V.

```
        clr     b
        move    #$0,x0
        move    #$0,x1
        move    #$0,y0
        move    #$0,y1
        bset    #4,omr          ; ebd
;
sbr     dor     #60,_end
        mac     x0,y0,a x:(r0)+,x1      y:(r4)+,y1
        mac     x1,y1,a x:(r0)+,x0      y:(r4)+,y0
        add     a,b
        mac     x0,y0,a x:(r0)+,x1
        mac     x1,y1,a                 y:(r4)+,y0
        move    b1,x:$ff
_end
        bra     sbr
        nop
        nop
        nop
        nop
PROG_END
        nop
        nop


XDAT_START
;       org     x:0
        dc      $262EB9
        dc      $86F2FE
        dc      $E56A5F
        dc      $616CAC
        dc      $8FFD75
        dc      $9210A
        dc      $A06D7B
        dc      $CEA798
        dc      $8DFBF1
        dc      $A063D6
        dc      $6C6657
        dc      $C2A544
        dc      $A3662D
        dc      $A4E762
        dc      $84F0F3
        dc      $E6F1B0
        dc      $B3829
        dc      $8BF7AE
        dc      $63A94F
        dc      $EF78DC
        dc      $242DE5
        dc      $A3E0BA
        dc      $EBAB6B
        dc      $8726C8
        dc      $CA361
        dc      $2F6E86
        dc      $A57347
        dc      $4BE774
        dc      $8F349D
        dc      $A1ED12
        dc      $4BFCE3
        dc      $EA26E0
        dc      $CD7D99
        dc      $4BA85E
        dc      $27A43F
        dc      $A8B10C
        dc      $D3A55
        dc      $25EC6A
        dc      $2A255B
        dc      $A5F1F8
        dc      $2426D1
        dc      $AE6536
        dc      $CBBC37
        dc      $6235A4
        dc      $37F0D
        dc      $63BEC2
        dc      $A5E4D3
        dc      $8CE810
        dc      $3FF09
        dc      $60E50E
        dc      $CFFB2F
        dc      $40753C
        dc      $8262C5
        dc      $CA641A
```

```
        dc      $EB3B4B
        dc      $2DA928
        dc      $AB6641
        dc      $28A7E6
        dc      $4E2127
        dc      $482FD4
        dc      $7257D
        dc      $E53C72
        dc      $1A8C3
        dc      $E27540
XDAT_END

YDAT_START
;       org     y:0
        dc      $5B6DA
        dc      $C3F70B
        dc      $6A39E8
        dc      $81E801
        dc      $C666A6
        dc      $46F8E7
        dc      $AAEC94
        dc      $24233D
        dc      $802732
        dc      $2E3C83
        dc      $A43E00
        dc      $C2B639
        dc      $85A47E
        dc      $ABFDDF
        dc      $F3A2C
        dc      $2D7CF5
        dc      $E16A8A
        dc      $ECB8FB
        dc      $4BED18
        dc      $43F371
        dc      $83A556
        dc      $E1E9D7
        dc      $ACA2C4
        dc      $8135AD
        dc      $2CE0E2
        dc      $8F2C73
        dc      $432730
        dc      $A87FA9
        dc      $4A292E
        dc      $A63CCF
        dc      $6BA65C
        dc      $E06D65
        dc      $1AA3A
        dc      $A1B6EB
        dc      $48AC48
        dc      $EF7AE1
        dc      $6E3006
        dc      $62F6C7
        dc      $6064F4
        dc      $87E41D
        dc      $CB2692
        dc      $2C3863
        dc      $C6BC60
        dc      $43A519
        dc      $6139DE
        dc      $ADF7BF
        dc      $4B3E8C
        dc      $6079D5
        dc      $E0F5EA
        dc      $8230DB
        dc      $A3B778
        dc      $2BFE51
        dc      $E0A6B6
        dc      $68FFB7
        dc      $28F324
        dc      $8F2E8D
        dc      $667842
        dc      $83E053
        dc      $A1FD90
        dc      $6B2689
        dc      $85B68E
        dc      $622EAF
        dc      $6162BC
        dc      $E4A245
YDAT_END

;************************************************************************
```

```
;
;     EQUATES for DSP56303 I/O registers and ports
;
;     Last update: June 11 1995
;
;*******************************************************************************

       page    132,55,0,0,0
       opt     mex

ioequ   ident   1,0

;-------------------------------------------------------------------------
;
;       EQUATES for I/O Port Programming
;
;-------------------------------------------------------------------------

;       Register Addresses

M_HDR EQU $FFFFC9      ; Host port GPIO data Register
M_HDDR EQU $FFFFC8     ; Host port GPIO direction Register
M_PCRC EQU $FFFFBF     ; Port C Control Register
M_PRRC EQU $FFFFBE     ; Port C Direction Register
M_PDRC EQU $FFFFBD          ; Port C GPIO Data Register
M_PCRD EQU $FFFFAF          ; Port D Control register
M_PRRD EQU $FFFFAE          ; Port D Direction Data Register
M_PDRD EQU $FFFFAD          ; Port D GPIO Data Register
M_PCRE EQU $FFFF9F          ; Port E Control register
M_PRRE EQU $FFFF9E          ; Port E Direction Register
M_PDRE EQU $FFFF9D          ; Port E Data Register
M_OGDB EQU $FFFFFC          ; OnCE GDB Register


;-------------------------------------------------------------------------
;
;       EQUATES for Host Interface
;
;-------------------------------------------------------------------------

;       Register Addresses

M_HCR EQU $FFFFC2      ; Host Control Register
M_HSR EQU $FFFFC3      ; Host Status Register
M_HPCR EQU $FFFFC4     ; Host Polarity Control Register
M_HBAR EQU $FFFFC5     ; Host Base Address Register
M_HRX EQU $FFFFC6           ; Host Receive Register
M_HTX EQU $FFFFC7           ; Host Transmit Register

;       HCR bits definition
M_HRIE EQU $0               ; Host Receive interrupts Enable
M_HTIE EQU $1               ; Host Transmit Interrupt Enable
M_HCIE EQU $2               ; Host Command Interrupt Enable
M_HF2 EQU $3               ; Host Flag 2
M_HF3 EQU $4               ; Host Flag 3

;       HSR bits definition
M_HRDF EQU $0               ; Host Receive Data Full
M_HTDE EQU $1               ; Host Receive Data Empty
M_HCP EQU $2               ; Host Command Pending
M_HF0 EQU $3               ; Host Flag 0
M_HF1 EQU $4               ; Host Flag 1


;       HPCR bits definition
M_HGEN EQU $0               ; Host Port GPIO Enable
M_HA8EN EQU $1               ; Host Address 8 Enable
M_HA9EN EQU $2               ; Host Address 9 Enable
M_HCSEN EQU $3              ; Host Chip Select Enable
M_HREN EQU $4               ; Host Request Enable
M_HAEN EQU $5          ; Host Acknowledge Enable
M_HEN EQU $6             ; Host Enable
M_HOD EQU $8              ; Host Request Open Drain mode
M_HDSP EQU $9             ; Host Data Strobe Polarity
M_HASP EQU $A             ; Host Address Strobe Polarity
M_HMUX EQU $B              ; Host Multiplexed bus select
M_HD_HS EQU $C             ; Host Double/Single Strobe select
M_HCSP EQU $D             ; Host Chip Select Polarity
M_HRP EQU $E              ; Host Request Polarity
M_HAP EQU $F              ; Host Acknowledge Polarity
```

```
M_FDBA   EQU     $FFFFB6         ; EFCOP Data Base Address
M_FCBA   EQU     $FFFFB7         ; EFCOP Coefficient Base Address
M_FDCH   EQU     $FFFFB8         ; EFCOP Decimation/Channel Register


;------------------------------------------------------------------------
;
;       EQUATES for Phase Locked Loop (PLL)
;
;------------------------------------------------------------------------

;       Register Addresses Of PLL

M_PCTL EQU $FFFFFD         ; PLL Control Register

;       PLL Control Register

M_MF EQU $FFF  : Multiplication Factor Bits Mask (MF0-MF11)
M_DF EQU $7000 ; Division Factor Bits Mask (DF0-DF2)
M_XTLR EQU 15  ; XTAL Range select bit
M_XTLD EQU 16  ; XTAL Disable Bit
M_PSTP EQU 17  ; STOP Processing State Bit
M_PEN EQU 18   ; PLL Enable Bit
M_PCOD EQU 19  ; PLL Clock Output Disable Bit
M_PD EQU $F00000; PreDivider Factor Bits Mask (PD0-PD3)



;------------------------------------------------------------------------
;
;       EQUATES for BIU
;
;------------------------------------------------------------------------

;       Register Addresses Of BIU


M_BCR EQU $FFFFFB; Bus Control Register
M_DCR EQU $FFFFFA; DRAM Control Register
M_AAR0 EQU $FFFFF9; Address Attribute Register 0
M_AAR1 EQU $FFFFF8; Address Attribute Register 1
M_AAR2 EQU $FFFFF7; Address Attribute Register 2
M_AAR3 EQU $FFFFF6; Address Attribute Register 3
M_IDR EQU  $FFFFF5 ; ID Register

;       Bus Control Register

M_BA0W EQU $1F ; Area 0 Wait Control Mask (BA0W0-BA0W4)
M_BA1W EQU $3E0; Area 1 Wait Control Mask (BA1W0-BA14)
M_BA2W EQU $1C00; Area 2 Wait Control Mask (BA2W0-BA2W2)
M_BA3W EQU $E000; Area 3 Wait Control Mask (BA3W0-BA3W3)
M_BDFW EQU $1F0000 ; Default Area Wait Control Mask (BDFW0-BDFW4)
M_BBS EQU 21   ; Bus State
M_BLH EQU 22   ; Bus Lock Hold
M_BRH EQU 23   ; Bus Request Hold

;       DRAM Control Register

M_BCW EQU $3   ; In Page Wait States Bits Mask (BCW0-BCW1)
M_BRW EQU $C   ; Out Of Page Wait States Bits Mask (BRW0-BRW1)
M_BPS EQU $300 ; DRAM Page Size Bits Mask (BPS0-BPS1)
M_BPLE EQU 11  ; Page Logic Enable
M_BME EQU 12   ; Mastership Enable
M_BRE EQU 13   ; Refresh Enable
M_BSTR EQU 14  ; Software Triggered Refresh
M_BRF EQU $7F8000; Refresh Rate Bits Mask (BRF0-BRF7)
M_BRP EQU 23   ; Refresh prescaler

;       Address Attribute Registers

M_BAT EQU $3   ; Ext. Access Type and Pin Def. Bits Mask (BAT0-BAT1)
M_BAAP EQU 2   ; Address Attribute Pin Polarity
M_BPEN EQU 3   ; Program Space Enable
M_BXEN EQU 4   ; X Data Space Enable
M_BYEN EQU 5   ; Y Data Space Enable
M_BAM EQU 6    ; Address Muxing
M_BPAC EQU 7   ; Packing Enable
M_BNC EQU $F00 ; Number of Address Bits to Compare Mask (BNC0-BNC3)
M_BAC EQU $FFF000; Address to Compare Bits Mask (BAC0-BAC11)
```

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